

Integrated Device Technology, Inc. 6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)							
PCN #: A1908-03 DATE:  Product Affected: DFN-10 (Refer to Attachment II for the	12-Sep-2019 affected part#)	MEANS OF DISTINGUISHING CHANGED DEVICES:  □ Product Mark □ Back Mark □ Date Code □ Other  Lot # will have: "MS" prefix for Carsem, Malaysia (S site)					
Date Effective: 12-Dec-2019							
Contact: IDT PCN DESK		Attachment: Yes No					
E-mail: <pre>pcndesk@idt.com</pre>		Samples: Please contact your local sales representative for sample request.					
DESCRIPTION AND PURPOSE OF CHANGE:							
Die Technology Wafer Fabrication Process Assembly Process Equipment Material This notification is to advise our customers that IDT is adding Carsem, Malaysia (S site) as an alternate assembly facility. There is no change to the moisture performance.							
□ Tastina	nt I details the q	ualification results.					
RELIABILITY/QUALIFICATION SUMMARY:  Refer to qualification data shown in Attachment I.							
CUSTOMER ACKNOWLEDGMENT OF RECEIPT:  IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.  IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.							
Customer:	_	Approval for shipments prior to effective date.					
Name/Date:	E-	-Mail Address:					
Title:	Ph	none# /Fax# :					
CUSTOMER COMMENTS:							
IDT ACKNOWLEDGMENT OF RECEIPT:							
RECD. BY:		DATE:					



# PRODUCT/PROCESS CHANGE NOTICE (PCN)

**ATTACHMENT I - PCN # : A1908-03** 

PCN Type: Alternate Assembly Location & Change Material Sets

**Data Sheet Change:** None

No change in moisture sensitivity level (MSL)

## **Detail Of Change:**

This notification is to advise our customers that IDT is adding Carsem, Malaysia (S site) as an alternate assembly facility.

The material set details of the current and alternate assembly location is as shown in Table 1.

There is no change to the moisture performance rating but the material declaration will differ.

Table 1: Assembly Material Sets for The Existing and Alternate Assembly Location

	Existing	Alternate		
Material Set / Assembly	UTL - UTAC, Thailand	CRSS - Carsem, Malaysia (S site)		
Die Attach	8200T, 8006NS	QMI519		
Bonding Wire	Copper wire	Copper wire		
Mold Compound	G700LTD	G770HCD		



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## **ATTACHMENT I - PCN # : A1908-03**

## **Qualification Information and Qualification Data:**

**Affected Packages:** DFN-10

**Assembly Material:** Shown on page 2 of this attachment.

**Qual Plan & Results:** Tests are in accordance with JEDEC47 recommended tests.

**Qualification Vehicle:** DFN-10

		Test Results (Rej / SS)		
Test Description	Test Method	Lot 1	Lot 2	Lot 3
* Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0/25	0/25	0/25
* HAST - biased (130 °C/85% RH, 96 Hrs)	JESD22-A110	0/25	0/25	0/25
High Temperature Storage Bake (150°C, 1000 Hrs)	JESD22-A103	0/25	0/25	0/25
X-Ray Examination	IDT Spec. MAC- 3012	0/45	0/45	0/45
Ball Shear Test	JESD22-B117	0/5	0/5	0/5
Bond Pull Test	MIL-STD-883 (Method 2011)	0/5	0/5	0/5
Moisture Sensitivity Level, MSL	J-STD-20 / MSL 1, 260 °C	0/25	0/25	-

<sup>\*</sup> Tests were subjected to Preconditioning per JESD22-A113 prior to stress test



# PRODUCT/PROCESS CHANGE NOTICE (PCN)

# ATTACHMENT II - PCN #: A1908-03

## **Affected Part Numbers**

Part Number	Part Number	Part Number	
5PB1203NTGK	5PB1213NTGK	5V30202NTGI	
5PB1203NTGK8	5PB1213NTGK8	5V30202NTGI8	